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Docket No.: M4065.0248/P248-C
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Allen McTeer

Application No.: 10/656,182

Confirmation No.: 8422

Filed: September 8, 2003

Art Unit: 2815

For: A MULTI-LAYERED COPPER BOND PAD
FOR AN INTEGRATED CIRCUIT

Examiner: E. Lee

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated March 23, 2005 (Paper No. 20050310),
please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins
on page 2 of this paper.

Remarks begin on page 4 of this paper.